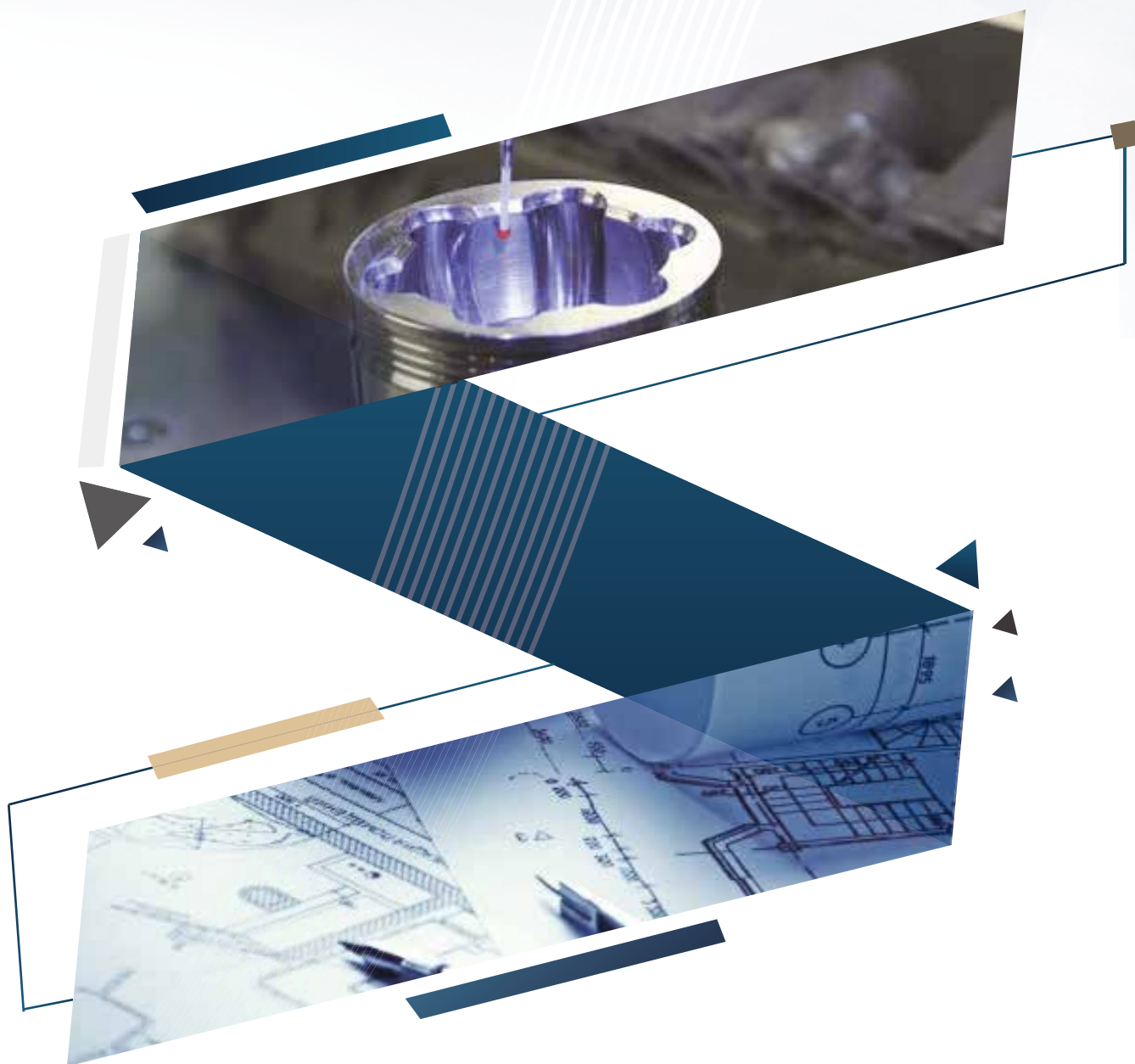




Sundi Precision Tools

A Professional High Precision Components and Mold Maker

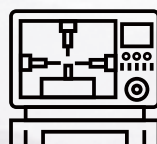
Precision Grinding



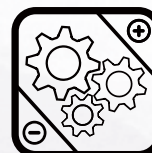
E.D.M Service



Metal CNC Service



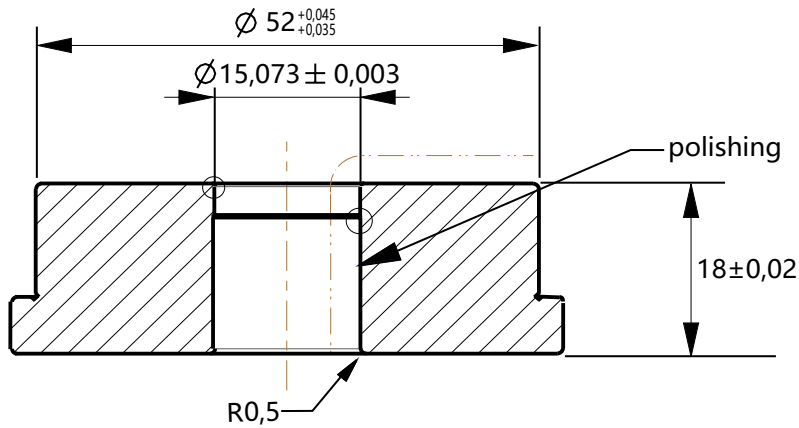
Mold and Fixture



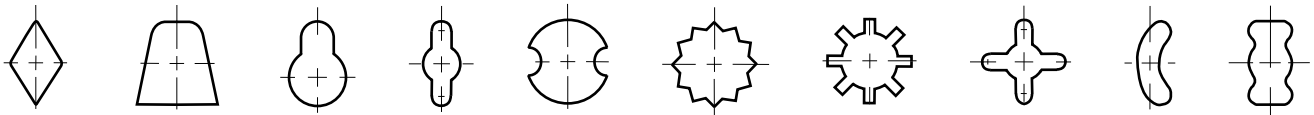
B DIE TOOLING



Round Dies



Special Shapes



Characteristics

Material: Carbide, HSS, rC60-63
Tolerance: $\pm 0.002\text{mm}$
Coating: DLC, TiCN, TiN
Manufactured to ISO standards where applicable.

Machining

Carbide can be inserted into steel
Polish inner side surface
3-5 times after coating

Note

Material is from reliable suppliers
Strong processing experience
Technical support

Product Showcase



Carbide dies

Mirror polishing



Deep Draws

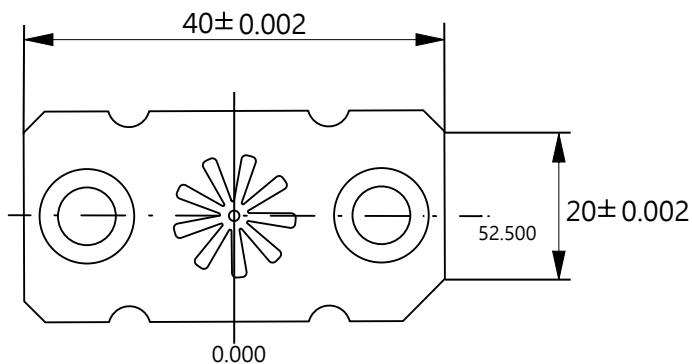
Insert the carbide dies into the steel



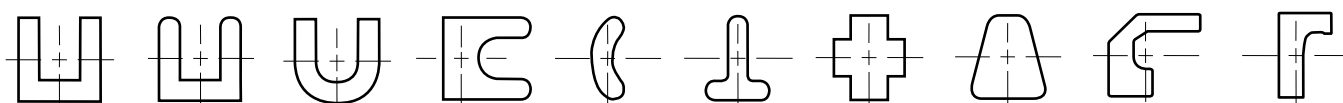
Dies with two parts

Good accuracy and great surface smooth

Square Dies



Special Shapes



Square Dies

Material: Carbide, HSS, HRC60-63

Tolerance: $\pm 0.002\text{mm}$

Coating: DLC, TiCN, TiN

Manufactured to ISO standards where applicable

Machining

Wire Cutting with $\pm 0.002\text{mm}$

Smooth finish

Tight clearance

Note

Multipass processes

Design and manufactured to meet different needs

Product Showcase



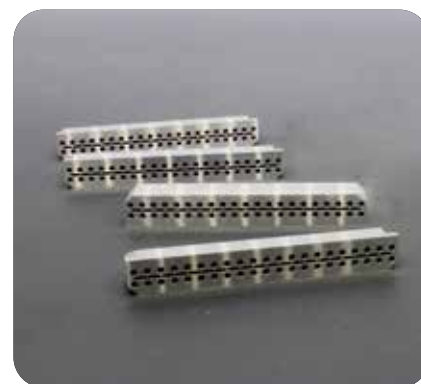
Carbide dies

For progressive die stamping



Die Components

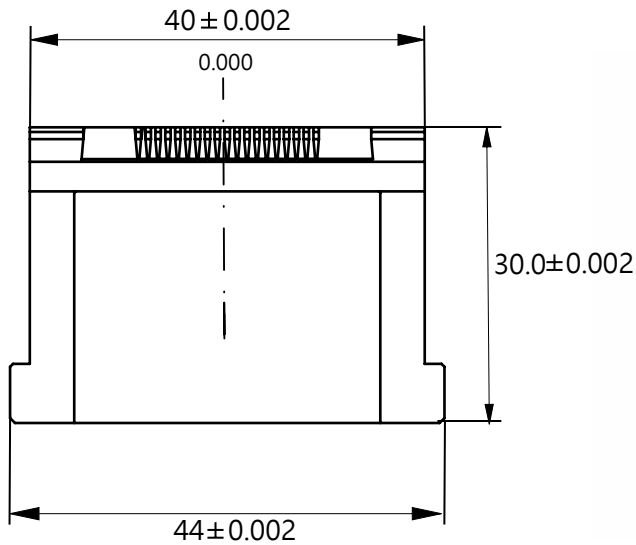
Working in the electronics industry



Carbide die

Small holes, no burrs, tight accuracy

Bar Cut Dies



Characteristics

Minimum 1M punching times
Various complex shapes
Tight accuracy and finish

Machining

Optical profile grinding for all slots
DLC coating to extend the working life
Teeth with Min width of 0.2 and Max depth of 6mm

Note

Working for semiconductor packaging
Material is from reliable suppliers
Specially manufactured to meet the highest demands of technology

Product Showcase



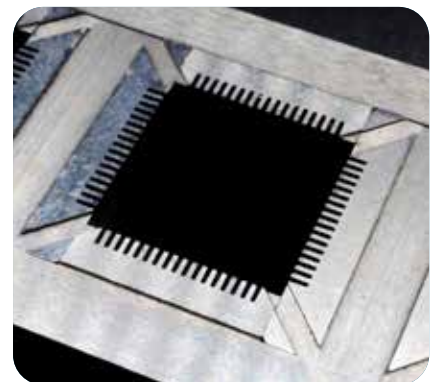
Carbide Die Component

DLC coating



Cut Die

Harden material Asp23 with HRC62-64



Carbide Cut Dies

Working in the semiconductor

Grade List

Series	Grade	Cobalt content Co%	Density [g/cm ³]	Hardness [HRA]	TRS [MPa]	Compression Strength [MPa]	Yan's Modulus [GPa]	Grain Size [μm]
GF	GF30T	12.0	14.25	90.0	3600	5000	580	0.8~1.8
	GF40H	12.5	14.20	89.5	3700	4700	570	1.0~2.0
	GF50H	14.0	14.00	88.5	3800	4600	550	1.5~3.0
	GF55HH	16.5	13.80	87.4	3500	4200	540	1.0~4.0
GA	GA10H	6.0	14.90	90.5	2950	5200	620	0.5~5.0
	GA18	12.0	14.17	89.5	3600	5500	580	1.0~2.0
	GA20	13.5	14.05	90.0	3700	5300	550	0.5~1.5
GU	GU20	10.3	14.40	91.5	3800	5600	600	0.8
	GU40	15.0	13.90	90.5	4000	5300	540	0.8
UF	GU25UF	12.0	14.05	92.2	4400	6000	570	0.5